



Power MOSFETS

DATASHEET

LM20600NLI3A

N-Channel
Enhancement Mode MOSFET

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Quality Management Systems
ISO 9001:2015 Certificate

N-Channel Enhancement Mode MOSFET

Pin Description

| SOT-23 (TOP view) | Symbol | Symbol | N-Channel | Unit |
|-------------------|--------|------------------|-----------|-----------|
| | | V_{DSS} | 20 | V |
| | | $R_{DS(ON)-Max}$ | 60 | $m\Omega$ |
| | | ID | 3.2 | A |

Feature

- Lower Qg and Qgd for high-speed switching
- Reliable and Rugged
- ROHS Compliant & Halogen-Free

Applications

- Portable Equipment
- Load Switch

Ordering Information

| Orderable Part Number | Package Type | Form | Shipping | Marking |
|-----------------------|--------------|-------------|--------------------|---------|
| LM20600NLI3A | SOT-23 | Tape & Reel | 3000 / Tape & Reel | 05□□ |

Absolute Maximum Ratings ($T_J=25^\circ C$ Unless Otherwise Noted)

| Symbol | Parameter | | N-Channel | Unit |
|--------------|---------------------------------|------------------|------------|------------|
| V_{DSS} | Drain-Source Voltage | $T_A=25^\circ C$ | 20 | V |
| V_{GSS} | Gate-Source Voltage | | ± 12 | |
| T_J | Maximum Junction Temperature | $T_A=70^\circ C$ | 150 | $^\circ C$ |
| T_{STG} | Storage Temperature Range | $T_A=25^\circ C$ | -55 to 150 | $^\circ C$ |
| $I_{DM}^{①}$ | Pulse Drain Current Tested | $T_A=25^\circ C$ | 8 | A |
| I_D | Continuous Drain Current | | 3.2 | |
| | | $T_A=70^\circ C$ | 2.5 | A |
| P_D | Maximum Power Dissipation | $T_A=25^\circ C$ | 0.9 | |
| | | $T_A=70^\circ C$ | 0.6 | W |
| $I_{AS}^{②}$ | Avalanche Current, Single pulse | $L=0.1mH$ | 12 | |
| $E_{AS}^{②}$ | Avalanche Energy, Single pulse | $L=0.1mH$ | 7.2 | mJ |

Thermal Characteristics

| Symbol | Parameter | Rating | Unit |
|---------------|--|----------------|--------------|
| $R_{θJA}^{③}$ | Thermal Resistance-Junction to Ambient | $t \leq 10sec$ | $^\circ C/W$ |
| | | Steady State | $^\circ C/W$ |

Note ① : Max. current is limited by junction temperature

Note ② : UIS tested and pulse width are limited by maximum junction temperature $150^\circ C$

Note ③ : Surface Mounted on 1in² FR-4 board with 1oz.

N-Channel Electrical Characteristics ($T_J=25^\circ\text{C}$ Unless Otherwise Noted)

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|---|----------------------------------|--|------|------|-----------|------------------|
| Static Electrical Characteristics | | | | | | |
| $\mathbf{BV_{DSS}}$ | Drain-Source Breakdown Voltage | $V_{GS}=0\text{V}, I_{DS}=250\mu\text{A}$ | 20 | - | - | V |
| I_{DSS} | Zero Gate Voltage Drain Current | $V_{DS}=16\text{V}, V_{GS}=0\text{V}$ | - | - | 1 | μA |
| $V_{GS(\text{th})}$ | Gate Threshold Voltage | $V_{DS}=V_{GS}, I_{DS}=250\mu\text{A}$ | 0.5 | 0.7 | 1 | V |
| I_{GSS} | Gate Leakage Current | $V_{GS}=\pm 12\text{V}, V_{DS}=0\text{V}$ | - | - | ± 100 | nA |
| $R_{DS(\text{ON})}^{\text{(4)}}$ | Drain-Source On-state Resistance | $V_{GS}=4.5\text{V}, I_{DS}=3\text{A}$ | - | 50 | 60 | $\text{m}\Omega$ |
| | | $V_{GS}=2.5\text{V}, I_{DS}=2\text{A}$ | - | 66 | 86 | |
| g_{fs} | Forward Transconductance | $V_{DS}=5\text{V}, I_{DS}=3\text{A}$ | - | 7 | - | S |
| Dynamic Characteristics ⁽⁵⁾ | | | | | | |
| R_G | Gate Resistance | $V_{GS}=0\text{V}, V_{DS}=0\text{V},$ $\text{Freq.}=1\text{MHz}$ | - | 1.3 | - | Ω |
| C_{iss} | Input Capacitance | $V_{GS}=0\text{V},$ $V_{DS}=10\text{V},$ $\text{Freq.}=1\text{MHz}$ | - | 123 | - | pF |
| C_{oss} | Output Capacitance | | - | 30 | - | |
| C_{rss} | Reverse Transfer Capacitance | | - | 26 | - | |
| $t_{d(\text{ON})}$ | Turn-on Delay Time | $V_{GS}=10\text{V}, V_{DS}=10\text{V},$ $I_D=1\text{A}, R_{\text{GEN}}=6\Omega$ | - | 3.2 | - | nS |
| t_r | Turn-on Rise Time | | - | 2.6 | - | |
| $t_{d(\text{OFF})}$ | Turn-off Delay Time | | - | 10 | - | |
| t_f | Turn-off Fall Time | | - | 5 | - | |
| Q_g | Total Gate Charge | $V_{GS}=2.5\text{V}, V_{DS}=10\text{V}$ $I_D=3\text{A}$ | - | 1.8 | - | nC |
| Q_g | Total Gate Charge | $V_{GS}=4.5\text{V}, V_{DS}=10\text{V},$ $I_D=3\text{A}$ | - | 3.0 | - | |
| Q_{gs} | Gate-Source Charge | | - | 0.5 | - | |
| Q_{gd} | Gate-Drain Charge | | - | 0.9 | - | |
| Source-Drain Characteristics | | | | | | |
| $V_{SD}^{\text{(4)}}$ | Diode Forward Voltage | $I_{SD}=3\text{A}, V_{GS}=0\text{V}$ | - | 0.8 | 1.1 | V |
| t_{rr} | Reverse Recovery Time | $I_F=3\text{A}, V_R=0\text{V}$ | - | 11.6 | - | nS |
| Q_{rr} | Reverse Recovery Charge | | - | 3.6 | - | nC |

Note ⁽⁴⁾ : Pulse test (pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$).Note ⁽⁵⁾ : Guaranteed by design, not subject to production testing.

N-Channel Typical Characteristics

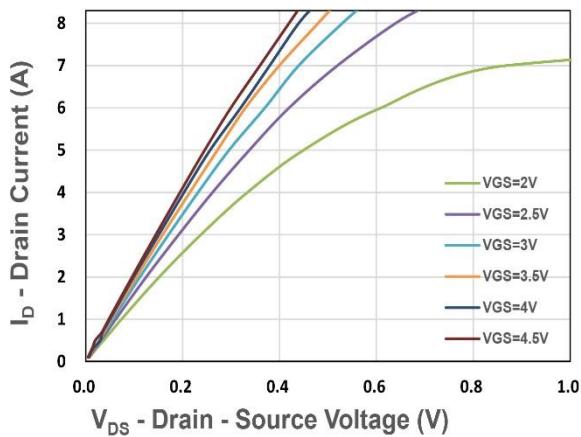


Figure 1. Output Characteristics

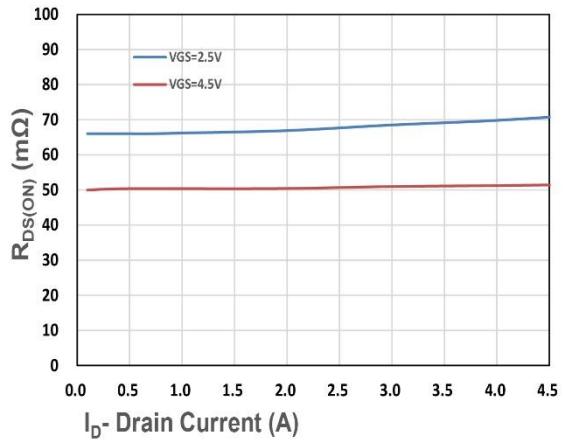


Figure 2. On-Resistance vs. ID

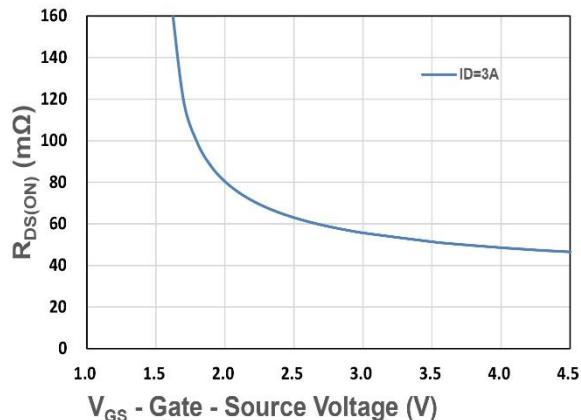


Figure 3. On-Resistance vs. VGS

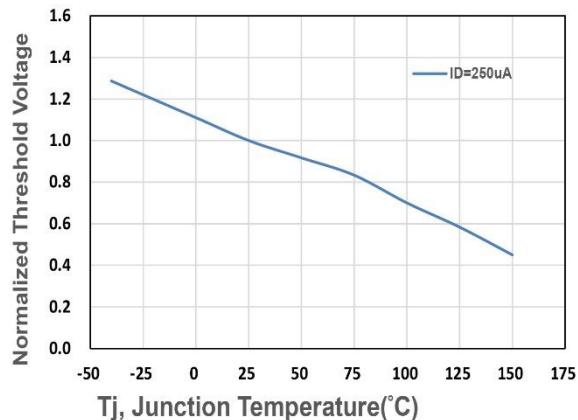


Figure 4. Gate Threshold Voltage

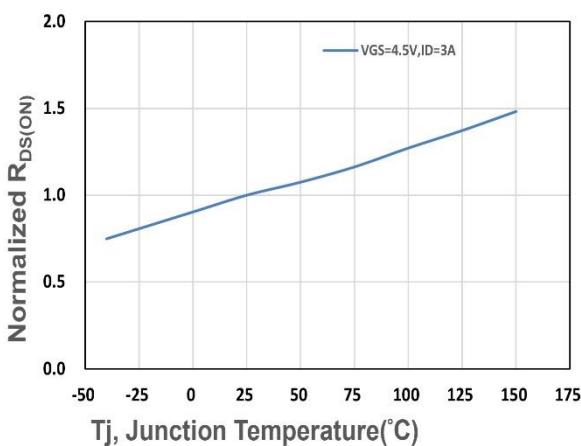


Figure 5. Drain-Source On Resistance

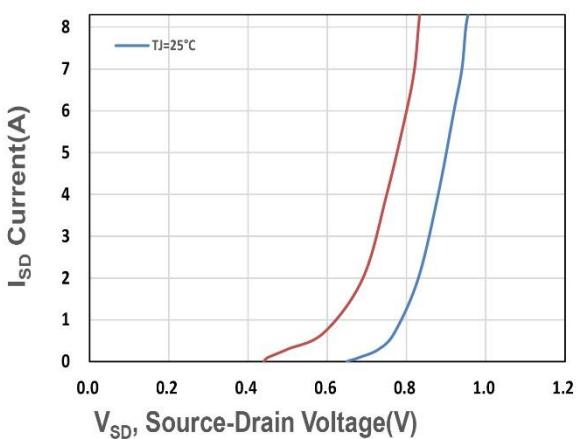


Figure 6. Source-Drain Diode Forward

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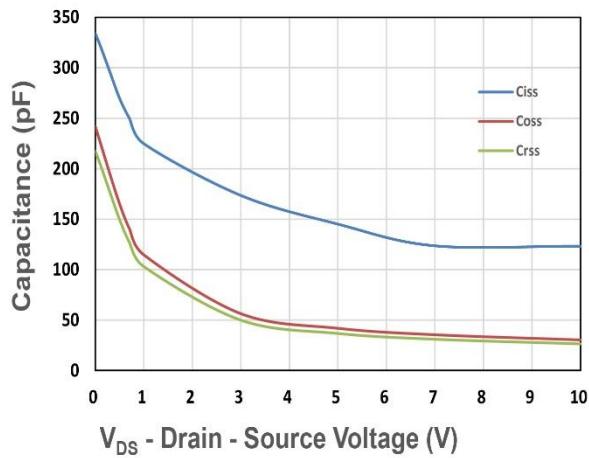


Figure 7. Capacitance

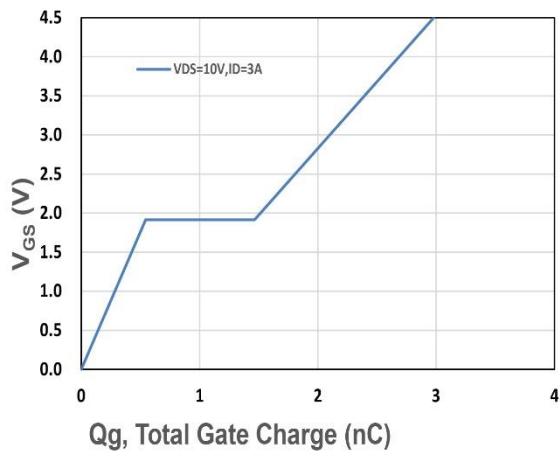


Figure 8. Gate Charge Characteristics

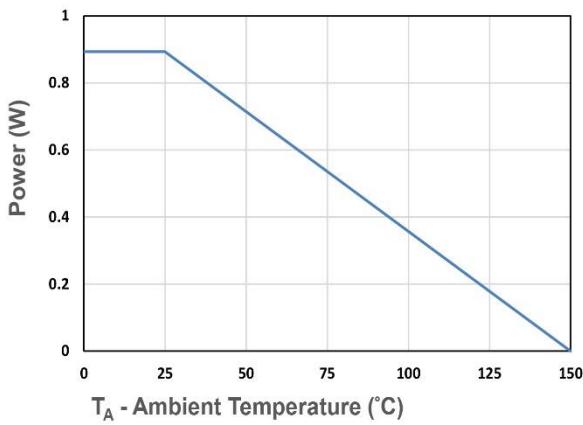


Figure 9. Power Dissipation

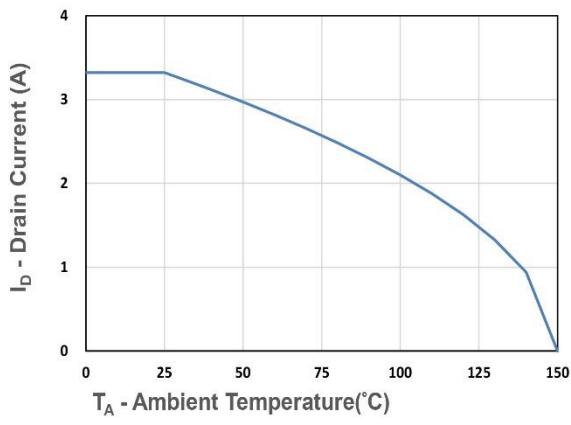


Figure 10. Drain Current

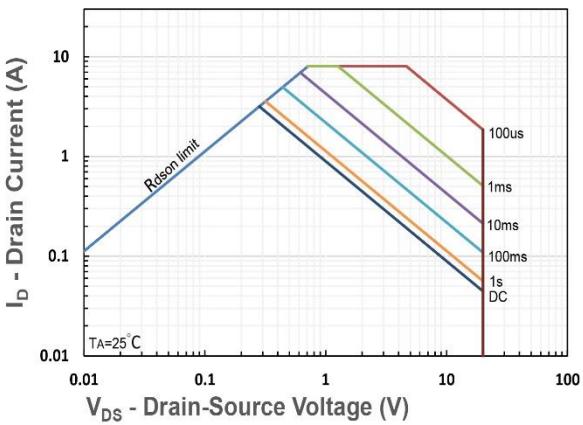


Figure 11. Safe Operating Area

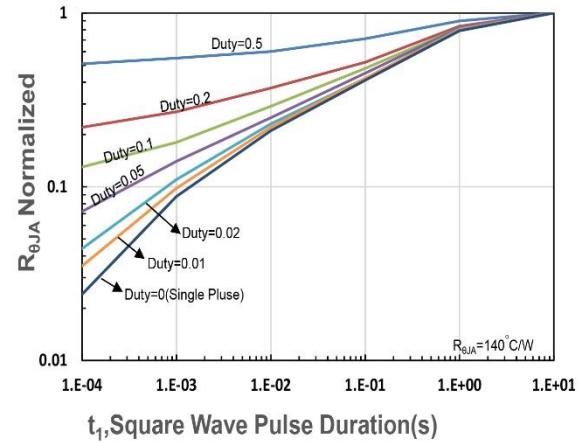


Figure 12. $R_{\theta JA}$ Transient Thermal Impedance